

RELIABILITY REPORT
FOR
MAX329EWE+
PLASTIC ENCAPSULATED DEVICES

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MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

Approved by
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Conclusion

The MAX329EWE+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX328/MA329 are monolithic CMOS analog multiplexers. The MAX328 is a single-ended, 1-of-8 device, and the MAX329 is a differential, 2-of-8 device. Designed to provide the lowest possible on- and off-leakages, these multiplexers switch signals from high source impedance, providing the mux operates into a high-input-impedance op amp or A/D converter. The MAX328/MAX329 are pin-for-pin replacements for the popular DG508/DG509 in these applications. Adding an external 40k resistor to each input makes the MAX328/MAX329 an excellent fault-tolerant multiplexer. Low leakage (less than 1pA at +25°C) and 2.5k on-resistance allow the circuit to sustain 110V AC faults indefinitely while maintaining an error of less than 40nV for normal signals (i.e., 1pA times 40k). The MAX328/MAX329 work equally well with a single supply of 10V to 30V or dual supplies of $\pm 5V$ to $\pm 18V$. They also perform well with unbalanced combinations of supply voltage, such as +12V and -5V or +5V and -15V. Low power dissipation (1.9mW with $\pm 15V$ supplies) allows use in portable applications.

II. Manufacturing Information

A. Description/Function:	Ultra-Low-Leakage, Single-Ended, Monolithic, CMOS Analog Multiplexer
B. Process:	M6H
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines, Malaysia
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	16-pin SOIC (W)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0301-0505
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	105°C/W
K. Single Layer Theta Jc:	22°C/W
L. Multi Layer Theta Ja:	70°C/W
M. Multi Layer Theta Jc:	23°C/W

IV. Die Information

A. Dimensions:	104 X 118 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/1.0%Si
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 13.7 \times 10^{-9}$$

$$\lambda = 13.7 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the M6H Process results in a FIT Rate of 0.30 @ 25C and 5.17 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (ESD lot NRSBB1001A D/C 9910, Latch-Up lot NRSBBA015B D/C 0030)

The AG45-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-600V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX329EWE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	NRSAB1001A, D/C 9910

Note 1: Life Test Data may represent plastic DIP qualification lots.